## **PRODUCT SPECIFICATIONS**

For Custom	ner:	PECIFICA	ATION		
Customer N	/lodel No		: APPROVAL	FOR SA	MPLE
Module No.	: M101B2	Date : 20	19.11.04		
			V	ersion :2	
Table of Co	ontents				
No.		Item			Page
1	Cover She	eet(Table of Contents)			
2	Revision F	Record			
3	General S	pecifications			
4	Pin Assign	nment			
5	Outline.Dr	awing			
6	Absolute N	Maximum Ratings			
7	Electrical	Specifications and Instru	uction Code		
8	Optical Ch	naracteristics			
9	Reliability	Test Items and Criteria			
10	Quality Le	vel			
11	Precaution	ns for Use of LCD Modu	ıles		
12	Packing R	eliability			
For Custor	ner's Acc	eptance:			
Approve	ed By		Comme	ent	
PREPARED CHECKED		CHECKED	VERIFIED DEP		VERIFIED BY R&D DEPT

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## 2. Revision Record

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## 3. General Specifications

M101B20-28-266-0101 is a TFT-LCD module. It is composed of a TFT-LCD panel, driver IC, FPC, a back light unit. The 10.1" display area contains  $800 \times 1280$  pixels and can display up to 16.7M colors. This product accords with ROHS environmental criterion.

Item	Contents	Unit	Note
LCD Type	TFT	-	
Display color	16.7M		1
Viewing Direction	ALL	O'Clock	
Operating temperature	-10~+50	$^{\circ}$	
Storage temperature	-20~+60	$^{\circ}$	
Module size	Refer to outline drawing	mm	2
Active Area(W×H)	135.36 x 216.58	mm	
Number of Dots	800×RGB×1280	dots	
Outline Dimensions	Refer to outline drawing	-	
Backlight	28-LEDs (white)	pcs	
Weight		g	
Data Transfer	LVDS	-	

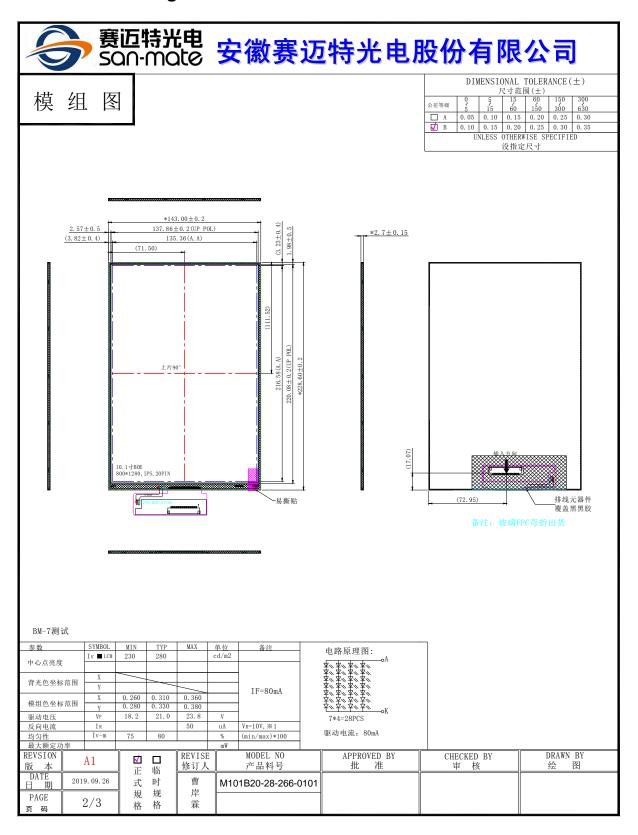
Note 1: Color tune is slightly changed by temperature and driving voltage.

Note 2: Without FPC and Solder.



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### 4. Outline. Drawing





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## 5.Pin Assignment

## DF14A-20P-1.25H

Pin No.	Symbol	I/P	Function	Remark
1	VDDIN	P	Power supply VDDIN=3.3V	
2	VDDIN	P	Power supply VDDIN=3.3V	
3	LED-EN	I	Backlight Enable Signal,3.3V~5V	
4	GND	P	Ground	
5	RXIN0N	I	-LVDS differential data	
6	RXIN0P	I	+LVDS differential data	
7	GND	P	Ground	
8	RXIN1N	I	-LVDS differential data	
9	RXIN1P	I	+LVDS differential data	
10	GND	P	Ground	
11	RXIN2N	I	-LVDS differential data	
12	RXIN2P	I	+LVDS differential data	
13	GND	P	Ground	
14	RX-CLKN	I	-LVDS differential clock input	
15	RX-CLKP	I	+LVDS differential clock input	
16	GND	P	Ground	
17	RXIN3N	I	-LVDS differential data	
18	RXIN3P	I	+LVDS differential data	
19	PWM	I	Backlight brightness PWM signal	
20	VLED	P	Power supply VLED=5~12V(Typ.)	

Note: I/O definition:

I: input, O: output, P: Power,

-: No Connection



## 6. Absolute Maximum Ratings(Ta=25℃)

#### 6.1 Electrical Absolute Maximum Ratings.(Vss=0V ,Ta=25℃)

Item	Symbol	Min.	Тур.	Max	Unit	Note
	$V_{DD}$	-0.3	3.3	3.6	V	
_	AVDD				V	
Power Supply Voltage	VGH				V	
Voltage	VGL				V	
	VLED	3.3	5	12	V	1, 2
Logic Signal Input	$V_{DDIO}$	-	-	-	V	
Current of LED	ILED	-	-	-	mA	

#### Notes:

- If the module is above these absolute maximum ratings. It may become permanently damaged.
   Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
- 2.  $V_{CC} > V_{SS}$  must be maintained.

#### 6.2 Environmental Absolute Maximum Ratings.

Item	Stor	age	Opera	Note	
item	MIN.	MAX.	MIN.	MAX.	Note
Ambient Temperature	<b>-20</b> ℃	60℃	-10℃	50℃	1,2
Humidity	-	-	-	-	3

- 1. The response time will become lower when operated at low temperature.
- 2. Background color changes slightly depending on ambient temperature.

The phenomenon is reversible.

3. Ta<=40°C:85%RH MAX.

Ta>=40°C:Absolute humidity must be lower than the humidity of 85%RH at 40°C.

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## 7.LED backlight specification(VSS=0V ,Ta=25℃)

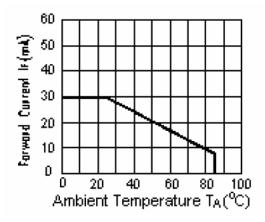
Ite	em	Symbol	Condition	Min	Тур	Max	Unit	Note
VLED Su	upply voltage	-	1	-3.3	5	12-	V	1
PWM Sig	nal Voltage	PWM_H		2.0	3.3	3.6	V	
PWM Sig	PWM Signal Voltage					0.5	V	
P\	PWM			0.2		1.1	MHZ	
LEI	LED-EN		-	-	3.3	5	V	2
Forward	Normal	I <sub>pn</sub>	7-chip series x	-	-	-	mA	
current	Dimming	$I_{pd}$	4	•	1	-	IIIA	

Note:

- 1: VLED=VLED(+)-VLED(-).
- 2:The current of LED is 20mA.

A LED drive in constant current mode is recommended.

3: LED power consumption is around 1.680W.



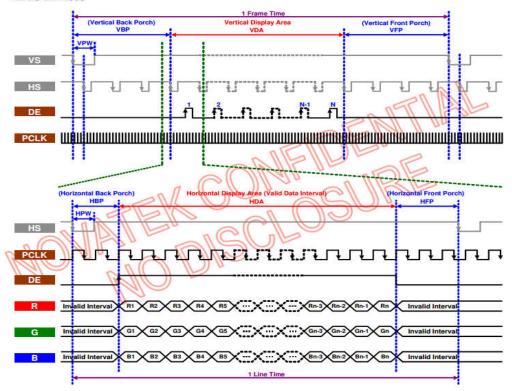
CIRCUIT DIAGRAM

**ILED VS TEMP** 

## 8. SIGNAL TIMING SPECIFICATION Signal timing

The equivalent input data format for LVDS HV mode and DE mode to RGB signal are shown below.

- LVDS DE mode



Note: There are no HS and VS information sent by LVDS interface in LVDS DE mode, the HS and VS in above figure are generated by driver IC internally.

#### - 800RGBx1280

(1) LVDS DE mode

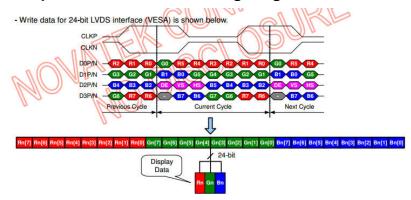
Parameter	Symbol	Min.	Тур.	Max.	Unit
DCLK Frequency	FDCLK	72.0	76.1	79.8	MHz
Horizontal Display Area	HDA		800		DCLK
Horizontal Blanking	HBP+HFP	110	160	200	DCLK
One Line Time	HBP+HAD+HFP	910	960	1000	DCLK
Vertical Display Area	VDA		1280	750	MAI
Vertical Blanking	VBP+VFP	38	41	50	(LH)
One Frame Time	VBP+VAD+VFP	1318	1321	1330	н

Parameter	Symbol	Min.	Typ.	Max.	Unit
DCLK Frequency	FDCLK	72.0	76,1	79.8	MHz
Horizontal Display Area	HDA		800	111 00	DCLK
Horizontal Back Porch	НВР	11 11	80 (Note)		DCLK
Horizontal Pulse Width	ньм (	حالم	-	70	DCLK
Horizontal Front Porch	HEP	30	80	120	DCLK
One Line Time	HBP+HAD+HFP	910	960	1000	DCLK
Vertical Display Area	VDA	7	1280	7.0	н
Vertical Back Porch	VBP	Ti	23 (Note)		н
Vertical Pulse Width	VPW	1	150	20	н
Vertical Front Porch	VFP	15	18	27	н
One Frame Time	VBP+VAD+VFP	1318	1321	1330	н

Note: HBP include HPW, and VBP include VPW

#### 9.0 SIGNAL TIMING WAVEFORMS OF INTERFACE SIGNAL

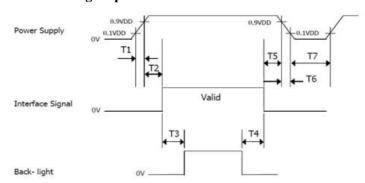
#### 9.1 Input Clock and Data Timing Diagram



#### **POWER SEQUENCE**

To prevent a latch-up or DC operation of the LCD module, the power on/off sequence shall be as shown in below Notes: 1. When the power supply VDD is 0V, keep the level of input signals on the low or keep high impedance. 2. Do not keep the interface signal high impedance when power is on. Back Light must be turn on after power for logic and interface signal are valid.

#### **Power-On/Off Timing Sequence:**



Parameter			Units	
	Min	Тур	Max	
T1	0	-	10	ms
T2	0	-	50	ms
Т3	200	-	-	ms
T4	200	-	-	ms
T5	0.5	-	50	ms
T6	0	-	10	ms
T7	500	-	-	ms

#### Notes:

- 1. When the power supply VDD is 0V,keep the level of input signals on the low or keep high impedance.
- 2. Do not keep the interface signal high impedance when power is on .Back light must be on after power for logic and interface signal are valid.

## 10. Optical Characteristics

Item	Sy	/mbol	Condition	Min.	Тур.	Max.	Unit	Note
Brightness		Вр	<i>θ</i> =0°	230	250	-	Cd/m <sup>2</sup>	1
Uniformity	2	⊴Bp	Ф=0°	75	80	-	%	1,2
Viewing	Hor	rizontal	Cr≥10		170		Deg	3
Angle	Vert	ical	01=10		170		Deg	0
Contrast Ratio		Cr	<i>θ</i> =0°	800	1000		-	4
Response		$T_r$	Φ=0°	1	35	1	ms	5
Time		$T_f$		-	33	-	ms	3
		Х			0.310			
	R	У			0.330			
		Y						
		Х			TBD			
Color of		у			TBD			
CIE		Υ		-0.05		+0.05		
Coordinate		Х	<i>θ</i> =0° Ф=0°	0.00	TBD	10.05		1,6
	G	у	Ψ-0		TBD			
		Υ						
		Х			TBD			
	В	у			TBD			
		Υ			-			
NTSC Ratio		S		-	60	-	%	

Note: The parameter is slightly changed by temperature, driving voltage and materiel

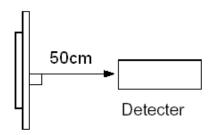
Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 (Φ8mm)

Measuring condition:

① Measuring surroundings: Dark room.

② Measuring temperature: Ta=25℃.

③ Adjust operating voltage to get optimum contrast at the center of the display. Measured value at the center point of LCD panel after more than 5 minutes while backlight turning on.

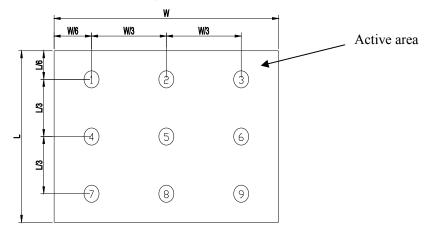


Note 2: The luminance uniformity is calculated by using following formula.

 $\triangle$ Bp = Bp (Min.) / Bp (Max.)×100 (%)

Bp (Max.) = Maximum brightness in 9 measured spots

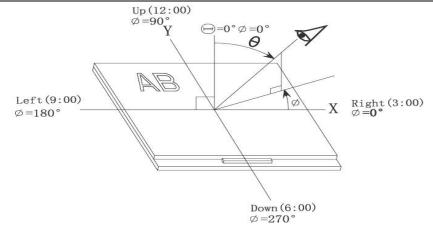
Bp (Min.) = Minimum brightness in 9 measured spots.



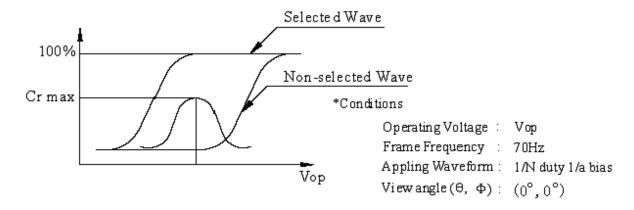
Note 3: The definition of viewing angle: Refer to the graph below marked by  $\theta$  and  $\Phi$ 



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Note 4: Definition of contrast ratio.( Test LCD using DMS501)



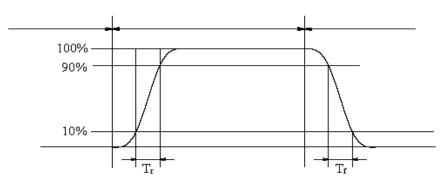
$$Contrast \ ratio(Cr) = \frac{Brightness \ of \ selected \ dots}{Brightness \ of \ non-selected \ dots}$$

Note 5: Definition of Response time. (Test LCD using DMS501):

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.

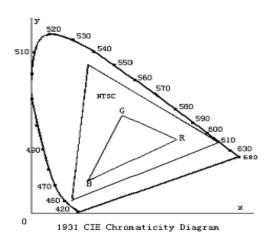


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The definition of response time

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.

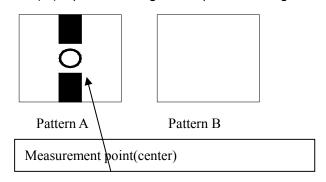


**Color gamut:** 

$$S = \frac{area \ of \ RGB \ triangle}{area \ of \ NTSC \ triangle} \times 100\%$$

Note 7: Definition of cross talk.

Cross talk ratio(%)=|pattern A Brightness-pattern B Brightness|/pattern A Brightness\*100



Electric volume value=3F+/-3Hex

## 11. Reliability Test Items and Criteria

No	Test Item	Test condition	Criterion
1	High Temperature Storage	60°C±2°C 96H Restore 2H at 25°C Power off	
2	Low Temperature Storage	-20°C±2°C 96H Restore 2H at 25°C Power off	d After to ation
3	High Temperature Operation	50°C±2°C 96H Restore 2H at 25°C Power on	1. After testing, cosmetic and electrical defects should not
4	Low Temperature Operation	-10°C±2°C 96H Restore 4H at 25°C Power on	happen.  2. Total current consumption should not be more than twice
5	High Temperature/Humidity Operation	40°C±2°C 90%RH 96H Power on	of initial value.
6	Temperature Cycle	-10°C → 50°C  30min 5min 30min  after 5 cycle, Restore 2H at 25°C  Power off	
7	Vibration Test	10Hz~150Hz, 100m/s <sup>2</sup> , 120min	Not allowed cosmetic
8	Shock Test	Half- sine wave,300m/s <sup>2</sup> ,11ms	and electrical defects.
9	ESD Test	Air discharge:+/-6KV, Contact discharge:+/-2KV,	

Note: Operation: Supply 2.8V for logic system.

The inspection terms after reliability test, as below

ITEM	Inspection
Contrast	CR>50%
IDD	IDD<200%
Brightness	Brightness>60%
Color Tone	Color Tone+/-0,05

### 12 Quality level

#### 12.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects(such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

#### 12.2 Definition of inspection range

For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).

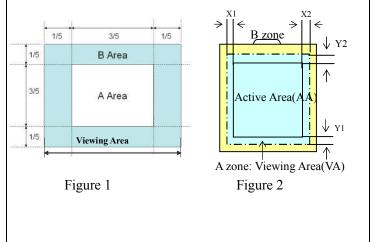
A area : center of viewing area B area : periphery of viewing area

C area : Outside viewing area

For other defects, dividing two areas to make a judgment (according figure 2).

A zone : Inside Viewing area B zone : Outside Viewing area

X1(A.A~V.A): 2mm X2(A.A~V.A): 2mm Y1(A.A~V.A): 2mm Y2(A.A~V.A): 2mm



#### 12.3 Inspection items and general notes

12.5 11	12.0 mapeedion itema and general notes						
General notes	<ul> <li>1.Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and HNH.</li> <li>2.Viewing area should be the area which HNH guarantees.</li> <li>3.Limit sample should be prior to this Inspection standard.</li> <li>4.Viewing judgment should be under static pattern.</li> <li>5.Inspection conditions Inspection distance: 250 mm (from the sample) Temperature : 25±5 °C Inspection angle : 45 degrees in 12 o'clock direction (all defects in viewing area should be inspected from this direction)</li> </ul>						
Inspection items	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon doesn't change with voltage					
items	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage					



Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass
Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display
Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction
Glass defect	Glass crack, Shaved corner of glass, Surplus glass
PCB defect	Components assembly defect

## 12.4 Outgoing Inspection level

Outgoing Inspection	Inspection conditions		Inspection				
standard	mapection conditions	Min.	Max.	Unit	IL	AQL	
Major Defects See 8.3 general notes		5	See 8.5	5	II	0.065	
Minor Defects See 8.3 general notes		S	ee 8.5		Ш	0.065	
Note: Sampling standard conforms to GB2828							

### 12.5 Inspection Items and Criteria

			Judgment standard					
	Inspection items			Category	Acceptable number			
				Category	A zone	B zone		
				Ф<=0.20	Neglected	Neglected		
	Black spot, White spot,	$b \uparrow$	В	0.20<Ф<=0.25		Neglected		
1	Pinhole, Foreign Particle, Particle	a	С	0.25<Ф<=0.3		Neglected		
'	in or on glass,	$\Phi=(a+b)/2(mm)$	D	0.3<Ф<=0.4				
	Scratch on glass	(a/b<2.5)	Е	0.4<Ф<=0.5				
			То	tal defective point(B,C)		-		
	4		Α	W<=0.03	Neglected	Neglected		
	Black line, White line, and Particle Between Polarizer and glass, Scratch on glass  L/W>=2.5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	В	0.03 <w<=0.05 L&lt;=3.0</w<=0.05 	-	Neglected		
2		etween   L:Length(mm)	С	0.05 <w<=0.1 L&lt;=3.0</w<=0.1 	-	Neglected		
_			D	0.05 <w<=0.1 L&lt;=4.0</w<=0.1 	-	-		
			Е	W>0.1 L>4.0	-	-		
			Total defective point(B,C)		-	-		
3	Bright spot		any size		none	none		
4	Contrast		А Ф<0.2		Neglected	Neglected		



Ī	variation			22 + 22			
	variation		В 0.2<Ф<=0.3		-		
		b	С	0.3<Ф<=0.4	-		
				0.4<Ф	-		
	$\begin{vmatrix} \leftarrow & \\ a \\ \Phi = (a+b)/2 \text{(mm)} \end{vmatrix}$		То	tal defective point(B,C)	-		
5	Bubble inside cell		any size		none	none	
6	Polarizer defect (if Polarizer is	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.	Refer to item 1 and item 2.				
	used)	Bubble, dent and	Α	Ф<=0.1	Neglected	Neglected	
		convex	В	0.1 <Ф<=0.2	-	Neglected	
			С	0.2 <Ф<=0.3	-	-	
7	Surplus glass	Stage surplus glass  Surrounding surplus glass	B<=0.3mm  Should not influence outline dimension and assembling.				
8	Open segment or o	open common	No	t permitted			
9	Short circuit			Not permitted			
10	False viewing direction			Not permitted			
11	Contrast ratio uneven			According to the limit specimen			
12	Crosstalk			According to the limit specimen			
13	Black /White spot(display)			Refer to item 1			
14	Black /White line(display)			Refer to item 2			

				Judgment standard			
Inspection items				Catego	ory(applicat	tion: B zone)	Acceptable number
15	Glass defect crack	i )The front of lead terminals	A	a≤ t,	b≤1/5W,	c≤3mm	Max.3 defects allowed
		c					

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	В	Crack at two sides of lead terminals should not cover patterns and alignment mark	
ii )Surrounding crack-non-contact side  seal  c h a t  Inner border line of the seal  Outer border line of the seal	b <	Inner borderline of the seal	
iii) Surrounding crack- contact side  seal  t  Inner border line of the seal  Outer border line of the seal	b <	Outer borderline of the seal	
iv)Corner	В	a <= t, b <= 3.0, c <= 3.0  Glass crack should not cover patterns u and alignment mark and patterns.	

Inspection items	Judgment standard		
mapeculon tema	Category(application: B zone)		



		Component soldering: No cold soldering, short, open circuit, burr, tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2) lead defect: The lead lack must be less than 1/3 of its	Component  Lead  Component  Label L1>0
16	PCB defect	width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted	
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	Soldering tin is not permit in this area  Soldering tin is not permit in this area
			socket Base Board
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat

#### 13. Precautions for Use of LCD Modules

#### 13.1 Handling Precautions

- 13.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 13.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into

contact with your skin or clothes, promptly wash it off using soap and water.

- 13.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 13.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 13.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
  - Isopropyl alcohol
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 13.1.6 Do not attempt to disassemble the LCD Module.
- 13.1.7 If the logic circuit power is off, do not apply the input signals.
- 13.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
  - a. Be sure to ground the body when handling the LCD Modules.
  - b. Tools required for assembly, such as soldering irons, must be properly ground.
  - c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
  - d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

#### 13.2 Storage precautions

- 12.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 12.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :  $0^{\circ}$ C  $\sim 40^{\circ}$ C

Relatively humidity: ≤80%

- 12.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 13.2.4 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.